THE 28TH ASIA-PACIFIC SOFTWARE ENGINEERING CONFERENCE

6th - 9th December 2021 - Taiwan

APSEC 2021 Welcome Letter

The Asia-Pacific Software Engineering Conference (APSEC) has long been established as a premier regional conference that brings together researchers and practitioners from academia, industry and government to share the state of the art and the practice of software engineering, and to explore emerging challenges and solutions in software engineering innovation. APSEC 2021 will continue in the tradition of previous editions of this regional conference. As past APSEC series, the main research track features the most recent and significant innovations in the field of software engineering and all its sub-disciplines. We invite submissions of high quality research papers that describe original and unpublished results on all topics of both theoretical and empirical software engineering research.

APSEC 2021 will offer an extensive program of interest to academia, government and industry. It will include several distinguished keynote speakers and conference days of paper presentations and demos. A series of exciting tutorials to develop skills in various aspects of software engineering practices is of particular interest to industry. Co-located workshops offer forums for participants to present novel techniques and methods in particular sub-disciplines of software engineering.

PROMOTIONAL OPPORTUNITY

WHY BECOME A SPONSOR OF THE APSEC 2021

• Contribute to writing a page of the history of the software engineering research

• Exchange information and ideas with the world's software engineering elite

• Showcase your latest innovations

• Enjoy high media coverage both nationally and internationally

• Access and understand current research in state-of-the-art technologies

• Recruit high-level talents

• Pair with products, ideas, solutions in the world of research

We will provide opportunities for our sponsors, exhibitors and partners to be involved in conference activities and engage directly with our delegates.

We are at your disposal to help you build a partnership that will best fit your needs.

SPONSORSHIP PACKAGES

The sponsorship packages provide sponsors with broad visibility before and during the congress. 3 categories are offered:

Items	Benefits	GOLD US $ 3,000 (NTD. 84,000)	SILVER US $ 2,000 (NTD. 56,000)	BRONZE US $ 1,000 (NTD. 28,000)
EXHIBITION BOOTHS	Exhibition Booths	V	V	X
	Exhibitor badges	3	2	X
REGISTRATION	Free conference passes (including gala dinner vouchers)	4	2	1
CONFERENCE	Access to VIP lounge	V	V	V
	Acknowledgement announcement at the opening and closing ceremonies	V	V	X
	Speaking opportunity at the gala dinner (within 5 minutes)	V	X	X
	5 mins promotional video played preceding gala dinner	V	X	X
ON-SITE VISIBILITY	Material inside the conference bag (flyer / job post / brochure)	3 items	2 items	1 item
	Logo recognition on the acknowledgement banner	V	V	V
	Logo on session room projection during session admission	V	V	V
	Logo on theme banners	V	V	X
ONLINE VISIBILITY	Logo and link on the conference website (sponsors' page)	Top level	Second level	Third level
	Company description on the conference website	V	V	V
	Logo on the conference website homepage	V	V	X
	Logo on the email announcement	V	V	X
	Promotion videos played before session	1 minute	30 seconds	X
ADVERT INSERTION	Logo on program book acknowledgement page	V	V	V

SPONSORSHIP REGISTRATION FORM

On behalf of APSEC 2021, your support is highly appreciated.
Please return the completed form to the Industrial Chair via Email.

Contact Person：APSEC 2021 Industrial Chair | Chu-Ti Lin

Tel：+886-5-271-7227

Email: chutilin@mail.ncyu.edu.tw

General Information

Company Name	
Address	
Country	
Contact Person	
Tel (Office)	
Email	

Sponsorship Level *(Please complete the payment before September 06, 2021)*

Package Sponsorship	☐ Gold US $3,000 or NTD. 84,000
	☐ Silver US $2,000 or NTD. 56,000
	☐ Bronze US $1,000 or NTD. 28,000

Signature / Company Stamp	Date

Remittance Information

Beneficiary's Name	**Software Engineering Association, Taiwan**
Beneficiary's Bank	**DBS Bank (Taiwan) Ltd**
Payment Details	**Branch code 364**
Bank Address	**13F., No.399, Ruiguang Rd., Neihu Dist., Taipei City 114, Taiwan, R.O.C.**
Bank Account	**007004308635**
Swift Code	**DBSSTWTP**

Note:

- Any bank charges incurred should be fully covered by the sender.
- Payment is expected be settled before September 06, 2021. (Early payment is welcome)

THE 28TH ASIA-PACIFIC SOFTWARE ENGINEERING CONFERENCE

第28屆亞太軟體工程研討會

2021 年 12 月 6 日至 9 日 – 台灣

APSEC 2021 歡迎函

　　亞太軟體工程研討會(Asia-Pacific Software Engineering Conference, APSEC)是亞太軟體工程社群的重要盛會，每年均吸引約 200 篇的論文投稿，過去論文錄取率大約為 30%左右。APSEC 會議主題包含 Software Requirements Engineering、Software Architecture, Modelling & Design、Testing Verification and Validation、Debugging, Defect Prediction & Fault Localisation、Software Maintenance and Evolution、Model-Driven & Domain Specific Engineering、Cloud & Service-Oriented Computing、Empirical Software Engineering、Cyber-Physical Systems & IoT、Software Project Management, Configuration Management& Deployment、Software Engineering Tools & Environment、Open Source Development、Formal Methods 等，是軟體工程領域的頂尖國際研討會之一。2019 年台灣軟體工程學會獲得 APSEC 指導委員會(Steering Committee of Asia-Pacific Software Engineering Conference)之邀請，於 12 月初至馬來西亞 APSEC 2019 進行簡報爭取於台灣主辦 APSEC 研討會，2020 年三月正式接獲指導委員會的授權通知，確定台灣獲得 2021 年度 APSEC 之會議主辦權，這是台灣自 2005 年後睽違 15 年再度獲得 APSEC 主辦權。APSEC 2021 籌備團隊誠摯邀請您共襄盛舉。

難得的宣傳機會

為什麼要成為APSEC 2021的贊助商?

- 了解最新軟體工程研究現況
- 與國際與國內優秀的軟體工程專家進行交流
- 展現與宣傳貴公司的創新軟體技術與成果
- 招募軟體人才
- 產學合作

　　除了可參與國際研討會活動，此次會議也將有國內多所大專院校的師生與會，其中多位與會的老師在各校兼任重要行政職務(如電算中心主管與資工系主任)，且國外學術界與軟體相關產業也對此會議高度關注，我們將盡力促成贊助商與各單位的合作機會。

贊助方案

我們提供的三個贊助方案如下：

優惠項目		贊助方案		
		金級	銀級	銅級
		美金 $3,000 (台幣 84,000)	美金 $2,000 (台幣 56,000)	美金 $1,000 (台幣 28,000)
展示攤位	展示攤位	V	V	X
	參展證	3	2	X
會議註冊	免費會議註冊(包含晚宴入場卷)	4	2	1
會議期間	貴賓室使用權	V	V	V
	開幕與閉幕典禮特別致謝	V	V	X
	晚宴致詞與宣傳(5 分鐘)	V	X	X
	晚宴前播放 5 分鐘宣傳影片	V	X	X
實體會議能見度提升措施	會議提袋中夾帶文宣(例如宣傳單、徵才公告)	3 件	2 件	1 件
	Logo 呈列於致謝橫幅或旗幟	V	V	V
	會議空檔將 Logo 投放於會場布幕	V	V	V
	將 Logo 呈列於大會主題看板	V	V	X
	會場擺設贊助廠商立牌	V	V	X
線上會議能見度提升措施	大會網頁呈列贊助商的 Logo 和網頁連結	頂層	第二層	第三層
	大會網頁呈列贊助商介紹	V	V	V
	大會主網頁呈列贊助商 Logo	V	V	X
	Logo 呈列於大會發出的 email	V	V	X
	在各會議場次前播放宣傳影片	1 分鐘	30 秒	X
廣告置入	Logo 呈列於會議手冊	V	V	V

贊助報名表

謹代表 APSEC 2021 籌備團隊感謝您的大力支持。
請將表單填妥後回傳至 Industrial Chair 的 Email 信箱。

聯絡人：**APSEC 2021 Industrial Chair | 林楚迪**
Tel：+886-5-271-7227
Email: chutilin@mail.ncyu.edu.tw

敬請提供以下資訊

公司/單位名稱	
地址	
國家	
聯絡對象	
聯絡人電話	
聯絡人**Email**	

贊助等級 (敬請於 2021 年 9 月 6 日前完成匯款)

贊助方案	□ 金級　　　　美金 **$3,000**　or　台幣 **84,000**元
	□ 銀級　　　　美金 **$2,000**　or　台幣 **56,000**元
	□ 銅級　　　　美金 **$1,000**　or　台幣 **28,000**元

簽章 / 公司簽(圖)章	日期

匯款資訊

戶名	社團法人台灣軟體工程學會
銀行	星展銀行**(810)** 南京東路分行**(0364)**
帳號	**007004308635**

注意事項: **敬請於 2021 年 9 月 6 日前完成匯款。**